

# ASMT-QxBE-Nxxxx

## Super 0.5W Power PLCC-4 Surface Mount LED Indicator



### Data Sheet



Lead (Pb) Free  
RoHS 6 fully  
compliant



#### Description

The Super 0.5W Power PLCC-4 SMT LED is first Blue & Green mid-Power PLCC-4 SMT LEDs using InGaN chip technology. The package can be driven at high current due to its superior package design. The product is able to dissipate the heat more efficiently compared to the Power PLCC-4 SMT LEDs. These LEDs produce higher light output with better flux performance compared to the Power PLCC-4 SMT LED.

The Super 0.5W Power PLCC-4 SMT LEDs are designed for higher reliability, better performance, and operate under a wide range of environmental conditions. The performance characteristics of these new mid-power LEDs make them uniquely suitable for use in harsh conditions such as in automotive applications, and in electronics signs and signals.

To facilitate easy pick and place assembly, the LEDs are packed in EIA-compliant tape and reel. Every reel is shipped in single intensity and color bin, to provide close uniformity.

#### Features

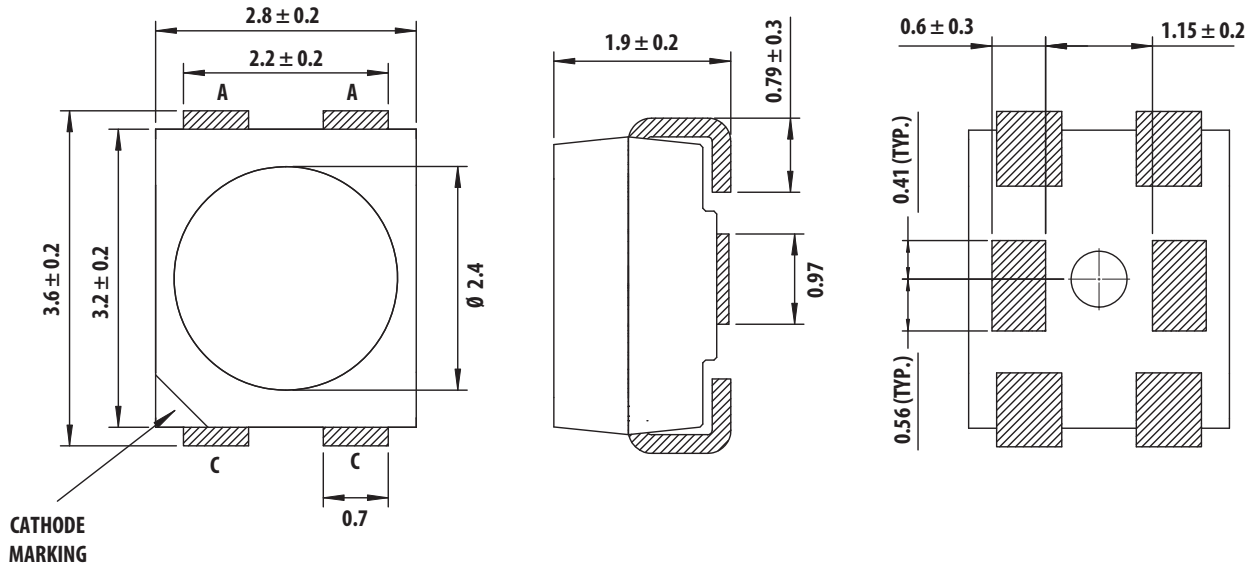
- Industry Standard PLCC 4 platform (3.2x2.8x1.9mm)
- High reliability package with enhanced silicone resin encapsulation
- High brightness with optimum flux performance using InGaN chip technologies
- Available in Blue and Green color
- Available in 8mm carrier tape & 7 inch reel
- Low Thermal Resistance 40°C/W
- Super wide viewing angle at 120 degree
- JEDEC MSL 2a

#### Applications

1. Electronic signs and signals
  - a. Decorative/Advertising Lighting
  - b. Channel Lettering
  - c. Signs Luminaire
  - d. RGB Backlighting

**CAUTION:** ASMT-QXBE-Nxxxx LEDs are ESD sensitive. Please observe appropriate precautions during handling and processing. Refer to Avago Application Note AN-1142 for additional details.

## Package Drawing



Notes:

1. All dimensions in millimeters
2. Lead polarity as shown in figure 13.
3. Terminal finish: Ag plating.
4. Encapsulation material: silicone resin.

Figure 1. Package Drawing

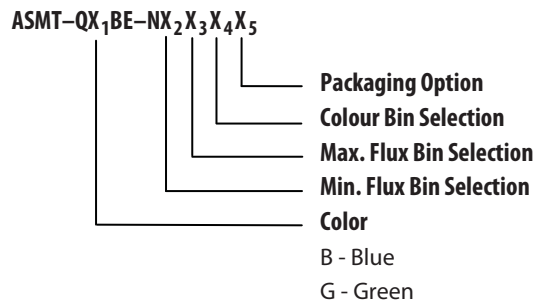
Table 1. Device Selection Guide

| Color | Part Number     | Luminous Flux, $\Phi_V^{[1]}$ (lm) |                |                | Test Current (mA) | Dice Technology |
|-------|-----------------|------------------------------------|----------------|----------------|-------------------|-----------------|
|       |                 | Min. Flux (lm)                     | Typ. Flux (lm) | Max. Flux (lm) |                   |                 |
| Blue  | ASMT-QBBE-N0B0E | 3.4                                | 4.8            | 7.0            | 150               | InGaN           |
| Green | ASMT-QGBE-NFH0E | 15.0                               | 23.0           | 33.0           | 150               | InGaN           |

Notes:

1.  $\Phi_V$  is the total luminous flux output as measured with an integrating sphere at mono pulse conditions.
2. Tolerance =  $\pm 12\%$

## Part Numbering System



**Table 2. Absolute Maximum Ratings ( $T_A = 25\text{ }^{\circ}\text{C}$ )**

| Parameters                          | ASMT-QWBE-Nxxxx                                   |
|-------------------------------------|---|
| DC Forward Current <sup>[1]</sup>   | 150 mA  |
| Peak Forward Current <sup>[2]</sup> | 300 mA  |
| Power Dissipation                   | 513 mW  |
| Reverse Voltage                     | -4V   |
| Junction Temperature                | 125 $^{\circ}\text{C}$                            |
| Operating Temperature               | -40 $^{\circ}\text{C}$ to +110 $^{\circ}\text{C}$ |
| Storage Temperature                 | -40 $^{\circ}\text{C}$ to +110 $^{\circ}\text{C}$ |

Notes:

1. Derate Linearly as shown in Figure 6.
2. Duty Factor = 10%, Frequency = 1kHz

**Table 3. Optical Characteristics ( $T_J = 25\text{ }^{\circ}\text{C}$ )**

|       |                 |                 | Peak Wavelength<br>$\lambda_{\text{PEAK}}$ (nm) | Dominant Wavelength $\lambda_D$<br>(nm) | Viewing Angle $2\theta_{1/2}$ <sup>[1]</sup><br>(Degrees) | Luminous Efficiency<br>$\eta_e$ (lm/W) | Total Flux / Luminous Intensity<br>$\Phi_V$ (lm) / $I_V$ (cd) |
|-------|-----------------|-----------------|---|---|---|--|---|
| Color | Part Number     | Dice Technology | Typ.  | Typ.                                    | Typ.  | Typ.                                   | Typ.  |
| Blue  | ASMT-QBBE-Nxxxx | InGaN           | 459.0   | 464.5                                   | 120   | 10                                     | 2.75  |
| Green | ASMT-QGBE-Nxxxx | InGaN           | 516.5   | 522.0                                   | 120   | 35                                     | 2.75  |

Notes:

1.  $\theta_{1/2}$  is the off-axis angle where the luminous intensity is  $1/2$  the peak intensity.

**Table 4. Electrical Characteristics ( $T_J = 25\text{ }^{\circ}\text{C}$ )**

| Part Number     | Forward Voltage VF (Volts) @ IF = 150 mA |      | Thermal Resistance $R_{\theta J-P}$ ( $^{\circ}\text{C}/\text{W}$ ) |
|-----------------|--|------|---|
|                 | Typ.                                     | Max. |   |
| ASMT-QBBE-N0B0E | 3.6                                      | 4.1  | 40  |
| ASMT-QGBE-NFH0E | 3.6                                      | 4.1  | 40  |

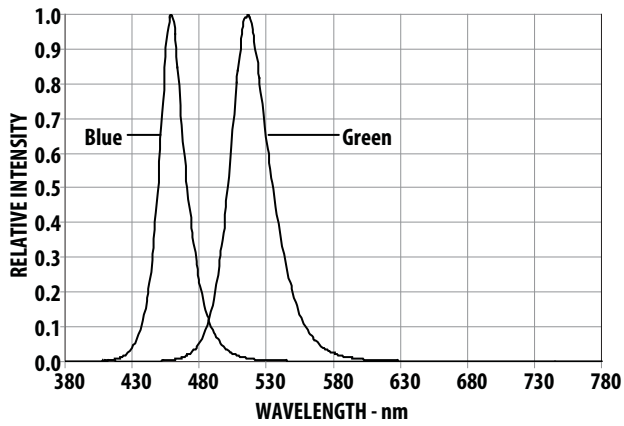


Figure 2. Relative Intensity Vs. Wavelength

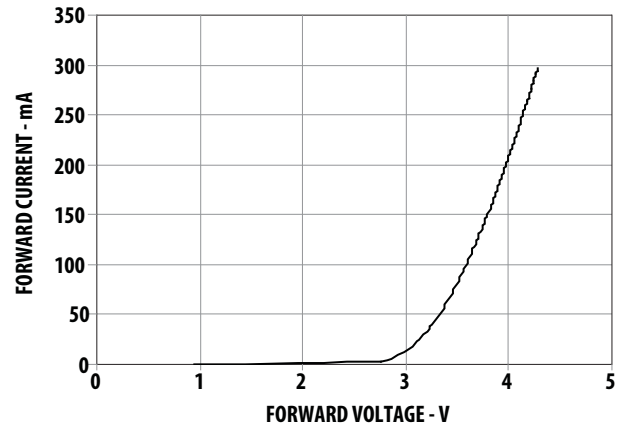


Figure 3. Forward Current Vs. Forward Voltage

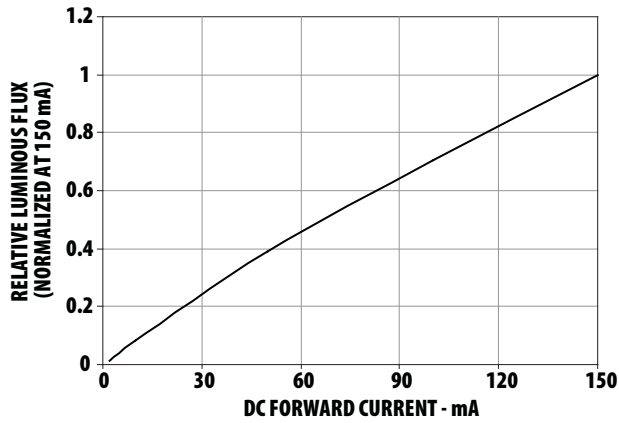


Figure 4. Relative Flux Vs. Forward Current

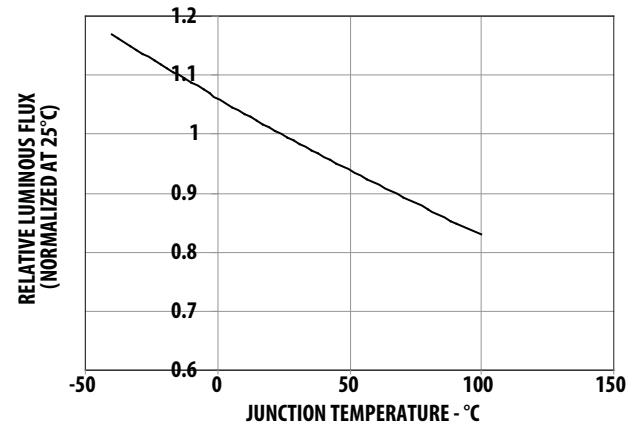


Figure 5. Relative Flux Vs. Temperature

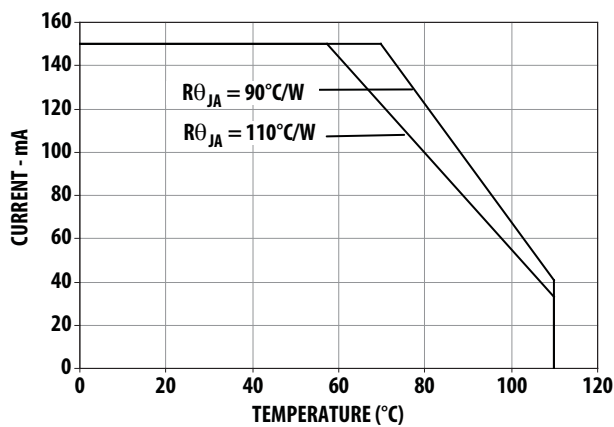


Figure 6a. Maximum Forward Current Vs. Ambient Temperature.  
Derated Based on  $T_{JMAX} = 125^{\circ}\text{C}$ ,  $R_{\theta JA} = 110^{\circ}\text{C/W}$  &  $90^{\circ}\text{C/W}$

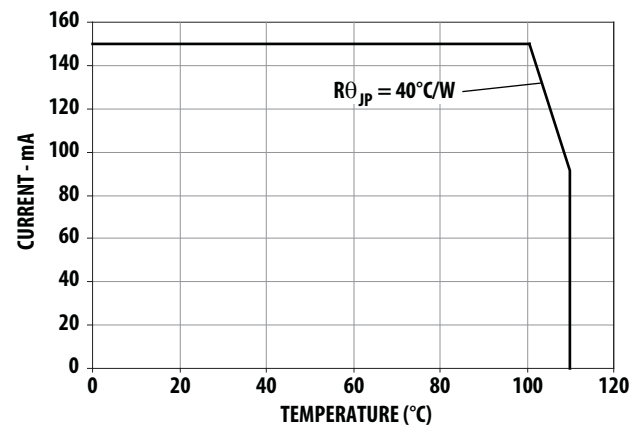


Figure 6b. Maximum Forward Current Vs. Solder Point Temperature.  
Derated Based on  $T_{JMAX} = 125^{\circ}\text{C}$ ,  $R_{\theta JP} = 40^{\circ}\text{C/W}$ .

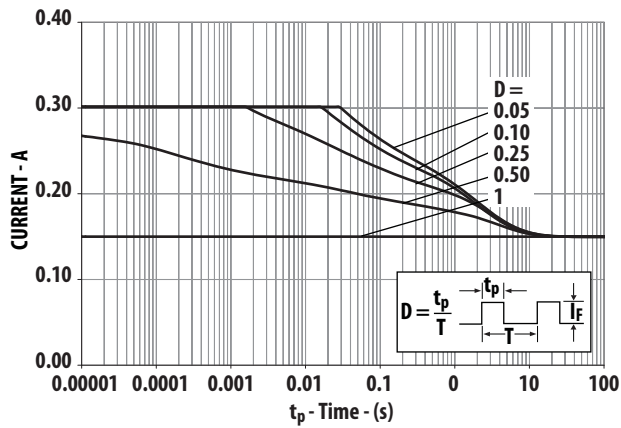


Figure 7a. Maximum Pulse Current Vs. Ambient Temperature.  
Derated Based on  $T_A = 25^\circ\text{C}$ ,  $R_{\theta JA} = 110^\circ\text{C/W}$ .

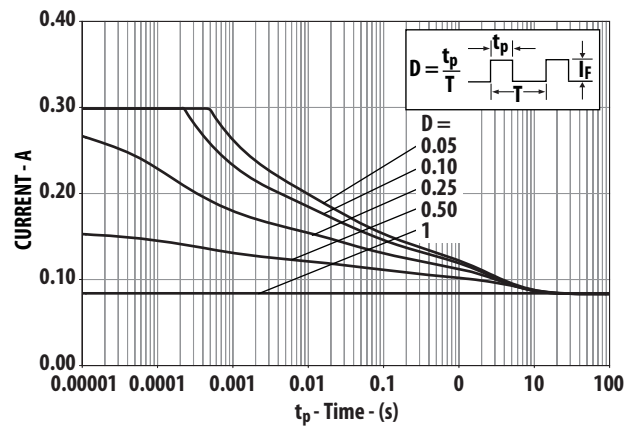


Figure 7b. Maximum Pulse Current Vs. Ambient Temperature.  
Derated Based on  $T_A = 85^\circ\text{C}$ ,  $R_{\theta JP} = 110^\circ\text{C/W}$ .

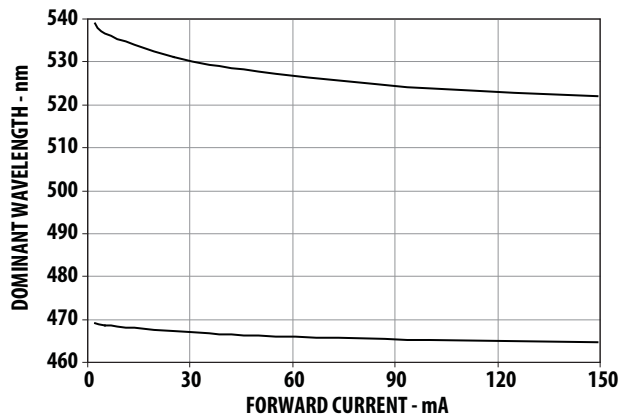


Figure 8. Dominant wavelength Vs. forward current.

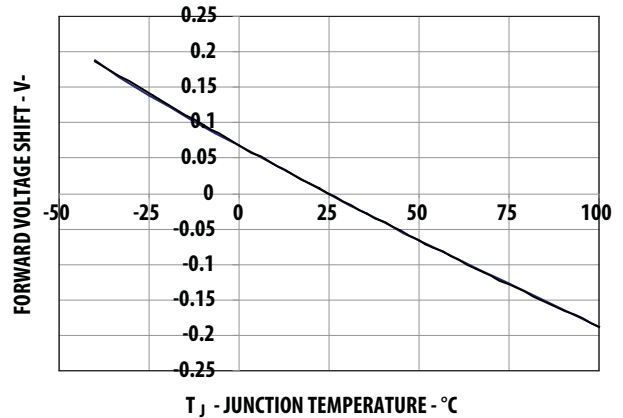


Figure 9. Forward Voltage Shift Vs. Temperature.

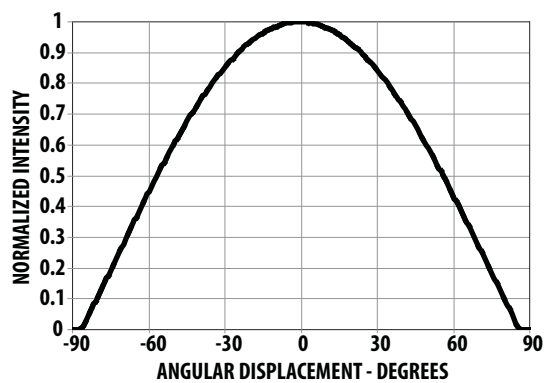
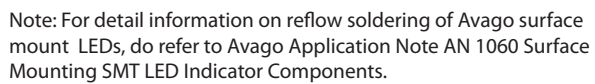
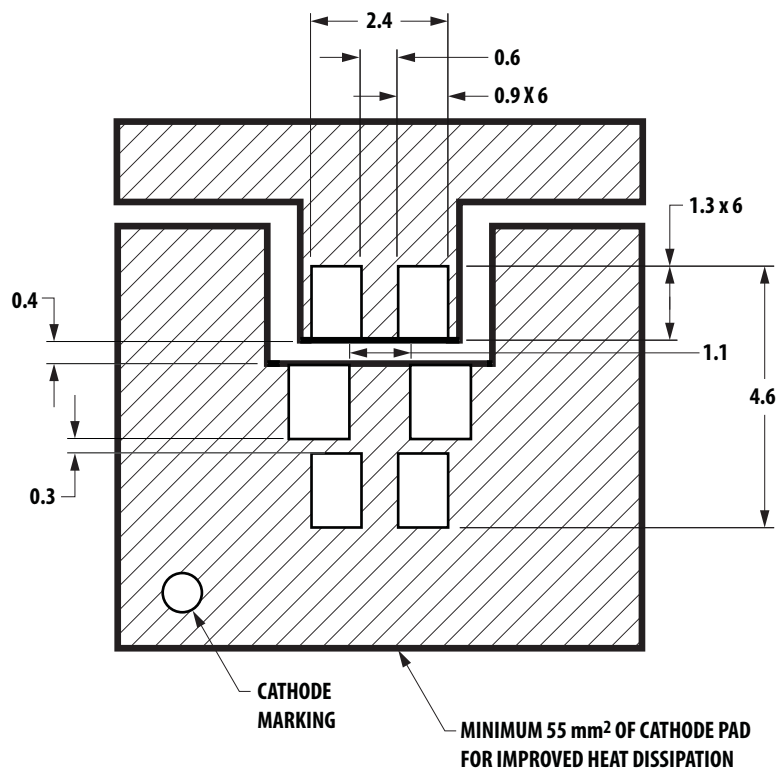


Figure 10. Radiation Pattern



**Figure 12. Recommended Pick and Place Nozzle Size**



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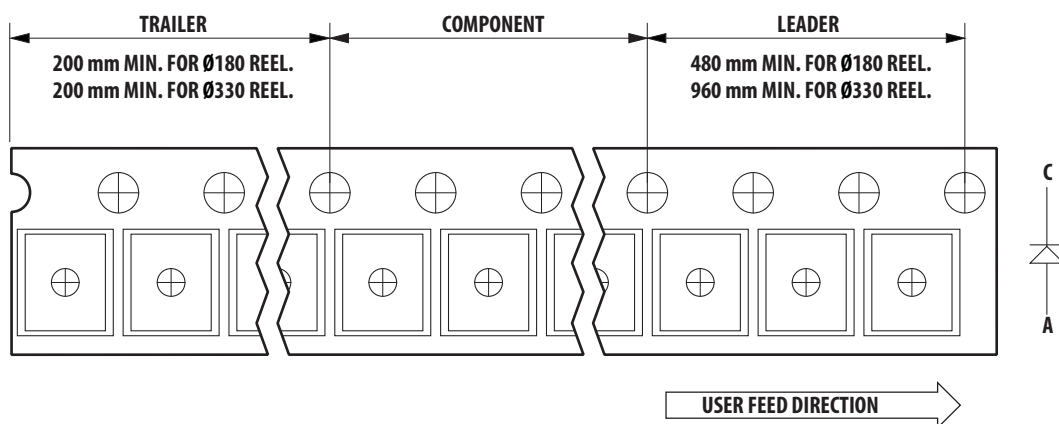


Figure 14. Tape Leader and Trailer Dimensions

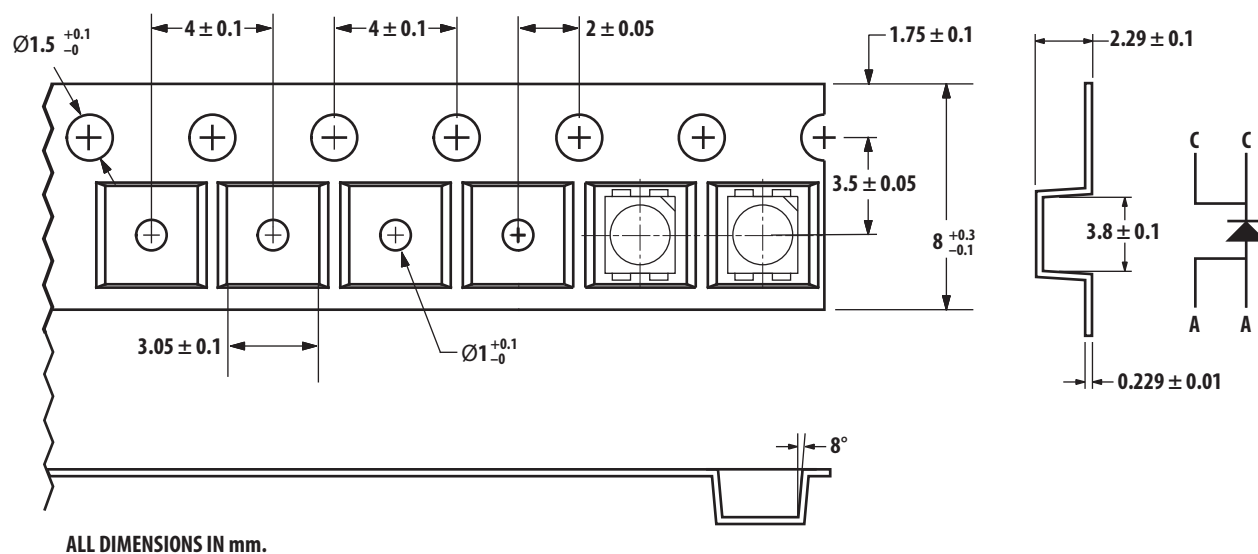


Figure 15. Tape Dimensions

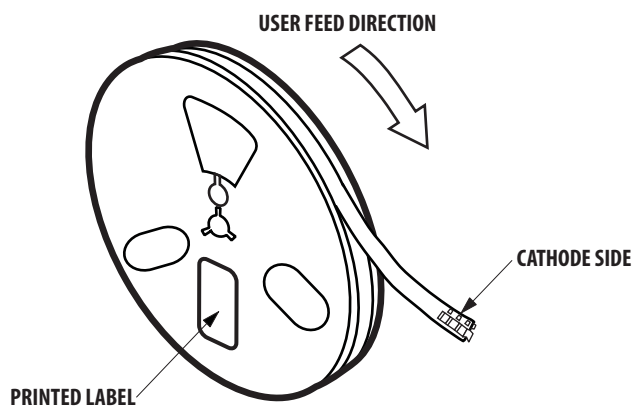


Figure 16. Reeling Orientation

## Handling Precaution

The encapsulation material of the product is made of silicone for better reliability of the product. As silicone is a soft material, please do not press on the silicone or poke a sharp object onto the silicone. These might damage the product and cause premature failure. During assembly or handling, the unit should be held on the body only. Please refer to Avago Application Note AN 5288 for detail information.

## Moisture Sensitivity

This product is qualified as Moisture Sensitive Level 2a per Jedec J-STD-020. Precautions when handling this moisture sensitive product is important to ensure the reliability of the product. Do refer to Avago Application Note AN5305 Handling of Moisture Sensitive Surface Mount Devices for details.

### A. Storage before use

- Unopen moisture barrier bag (MBB) can be stored at <40°C/90%RH for 12 months. If the actual shelf life has exceeded 12 months and the HIC indicates that baking is not required, then it is safe to reflow the LEDs per the original MSL rating.
- It is not recommended to open the MBB prior to assembly (e.g. for IQC).

### B. Control after opening the MBB

- The humidity indicator card (HIC) shall be read immediately upon opening of MBB.
- The LEDs must be kept at <30°C / 60%RH at all time and all high temperature related process including soldering, curing or rework need to be completed within 672 hours.

### C. Control for unfinished reel

- For any unused LEDs, they need to be stored in sealed MBB with desiccant or desiccator at <5%RH.

### D. Control of assembled boards

- If the PCB soldered with the LEDs is to be subjected to other high temperature processes, the PCB need to be stored in sealed MBB with desiccant or desiccator at <5%RH to ensure no LEDs have exceeded their floor life of 672 hours.

### E. Baking is required if:

- "10%" is Not Green and "5%" HIC indicator is Azure.
- The LEDs are exposed to condition of >30°C / 60% RH at any time.
- The LEDs floor life exceeded 672 hours.

Recommended baking condition: 60±5°C for 20 hours.

## Device Color (X<sub>1</sub>)

|   |       |
|---|-------|
| B | Blue  |
| G | Green |

## Flux Bin Select (X<sub>2</sub>X<sub>3</sub>)

Individual reel will contain parts from one bin only

|                |              |
|----------------|--------------|
| X <sub>2</sub> | Min Flux Bin |
| X <sub>3</sub> | Max Flux Bin |

## Flux Bin Limits

| Bin ID | Min. (lm) | Max. (lm) |
|--------|-----------|-----------|
| 0      | 3.40      | 4.30      |
| A      | 4.30      | 5.50      |
| B      | 5.50      | 7.00      |
| C      | 7.00      | 9.00      |
| D      | 9.00      | 11.50     |
| E      | 11.50     | 15.00     |
| F      | 15.00     | 19.50     |
| G      | 19.50     | 25.50     |
| H      | 25.50     | 33.00     |
| J      | 33.00     | 43.00     |
| K      | 43.00     | 56.00     |
| L      | 56.00     | 73.00     |

Tolerance of each bin limit = ± 12%

## Color Bin Select (X<sub>4</sub>)

Individual reel will contain parts from one full bin only.

| X <sub>4</sub> |                   |
|----------------|-------------------|
| 0              | Full Distribution |
| A              | 1 and 2 only      |
| B              | 2 and 3 only      |
| C              | 3 and 4 only      |
| G              | 1, 2 and 3 only   |
| H              | 2, 3 and 4 only   |
| Z              | Special binning   |

### Color Bin Limits

| Blue | Min. (nm) | Max. (nm) |
|------|-----------|-----------|
| 1    | 460.0     | 465.0     |
| 2    | 465.0     | 470.0     |
| 3    | 470.0     | 475.0     |
| 4    | 475.0     | 480.0     |

| Green | Min. (nm) | Max. (nm) |
|-------|-----------|-----------|
| 1     | 515.0     | 520.0     |
| 2     | 520.0     | 525.0     |
| 3     | 525.0     | 530.0     |
| 4     | 530.0     | 535.0     |

Tolerance of each bin limit =  $\pm 1$  nm

### VF Bin Limits

| Bin ID | Min. | Max. |
|--------|------|------|
| S5     | 3.20 | 3.50 |
| S6     | 3.50 | 3.80 |
| S7     | 3.80 | 4.10 |

Tolerance of each bin limit =  $\pm 0.1$  V

### Packaging Option (X5)

| Option | Test Current | Package Type | Reel Size |
|--------|--------------|--------------|-----------|
| E      | 150mA        | Top Mount    | 7 Inch    |

For product information and a complete list of distributors, please go to our web site: [www.avagotech.com](http://www.avagotech.com)

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